Lenovo P16 Gen 3

Version: 2.0 | 03/11/2026

Datasheet Specs

Product Name

Product Display Name	ThinkPad P16 Gen 3
Information Date	Sept 5 2025

SECTION I: SYSTEM OVERVIEW

Description	The Lenovo ThinkPad P16 is the ultimate mobile workstation for professionals who demand superior performance, reliability, and innovation. With a new, thinner, and lighter chassis design, it serves as a powerful desktop replacement while offering enhanced portability and usability.
Processor Support	Intel Core Ultra Series 2 – HX-Series (45W) Core 5, 7, and 9
Socket Type	BGA
Preloaded	Windows 11 Pro 64-bit (24H2) Windows 11 Home 64-bit Windows 11 Home Single Language 64-bit Windows 11 Home Chinese Language Edition 64-bit Ubuntu Linux 64-bit (Version 24.04) Fedora 40 Linux (depending on NVIDIA open source driver status) No Operating System
Supported	Ubuntu Linux 24.04 Cert only Red Hat Enterprise Linux (RHEL) 10.0 (depending on NVIDIA open source driver status)
Number of DIMM Slots	Up to 4 Slots
Channels	Single Channel w/ 1 DIMM Dual Channel w/ 2-4 DIMMs
Type	DDR5 SoDIMM ECC and non-ECC
ECC Support	Yes (16GB and 32GB SoDIMMs only)
Speed	Native: Up to 5600MT/s Actual: Up to 4800MT/s

Max DIMM Size	48GB
Max System Memory	192GB (non-ECC) 128GB (ECC)
Min System Memory	16GB
Soldered Memory	None
Storage Slots	3x M.2 2280
SATA	No
PCIe	Solid State Drive, 2x OPAL2 PCIe NVMe M.2 – TLC
SAS	No
Interface	PCIe Gen 5 Performance or Gen 4 Value
Security	OPAL2 for NVMe SSD
Optional Hard Disk Drive Controllers	No
Disclaimers	Triple slot storage is available with all CPU & GPU options
Integrated Graphics	Processor Graphics Intel® Arc Pro Graphics Utilized via “Hybrid Mode” in BIOS
Discrete Graphics	NV RTX PRO 1000 Blackwell, 2000 Blackwell, 3000 Blackwell, 4000 Blackwell, 5000 Blackwell
Adapter	None
Bus Interface	PCI Express 5.0
Resolutions	WUXGA (FHD+) / WQUXGA (UHD+) / 3.2k T-OLED Touch
Resolution	5MP RGB Camera or 5MP RGB + IR Hybrid Camera
Frames per Second	30 fps
Focus	Fixed 50cm
Camera Interface	USB
IR Camera	Yes
Number of Keys	US : 105 / UK : 106 / JP : 110
Numpad	Yes
Size	100% ISO
Function Key Features	Yes
Backlit	Yes
Keyboard size	CS25 KYB with numberpad
Key stroke	1.5mm
Key pitch	19.05mm
Keyboard backlight	Yes
Keyboard thickness	4.0mm
TrackPoint Details	CS22 TL TrackPoint (t=4.8mm)
Finger Print Reader Model	3.24 MoC Black Round FoP

Multi-Touch	Yes
Resolution	n/a
TouchPad/Trackpad thickness	3.6mm
TouchPad/Trackpad type	TrackPad
Trackpad size	115mm x 67.6mm
Trackpad material/finish	Glass like mylar surface
USB	2x USB-A (10Gbps)
Thunderbolt	1x USB-C (Thunderbolt™ 4) 2x USB-C (Thunderbolt™ 5)
HDMI	1x HDMI 2.1
Audio Combo Jack	1x Microphone & Headphone Combo Jack (3.5mm)
Media Card Reader	Dedicated SD Express 8.0 Card Reader (Backwards compatible with UHS-I & UHS-II) (MMC,SD,SDHC SDXC)
Smart Card Reader	Yes (optional)
Power Connector	DC-In via USB-C® (Thunderbolt™ 5) PD 3.1
Docking Port	Docking Via USB-C® (Thunderbolt™ 5) PD 3.1
VirtualLink	None
Network adapter	Full size 2.5Gbps RJ-45 port
Disclaimers	HDMI 2.1: Up to 8K/60Hz
Main	DC-In via USB-C® (Thunderbolt™ 5) PD 3.1
USB-C	see above
Disclaimers	normal charge via 140W and fast charge via 180W charger
Vendor	Intel
Count	1
EEPROM	16Mb SPI ROM
Speeds	2.5Gbps
Functions	Ethernet Connection I226
Connectors	Full size 2.5Gbps RJ-45 port
Model	5G: Rolling Wireless RW350R-GL 5G sub-6GHz CAT19/CAT18
Disclaimers	WWAN support country dependent
Model	Foxconn NXP NPC300 NFC
Vendor	Cirrus
Type	Soundwire Audio
Internal Speaker	2 channel
Connectors	Microphone & Headphone Combo Jack (3.5mm)
Chipset	Cirrus Logic Codec: CS42L43, Smart AMP: CS35L56
Number of Channels	2-channel DAC, 2-channel ADC, 2-channel Class D

Number of Bits/Audio Resolution	24bit / PCM-format
Sampling Rate (Recording/Playback)	Recording:48000Hz / Playback:48000Hz
Signal to Noise Ratio	Mic In: 90dB FSA Headphone Out@32ohm: 97dB FSA
Analog Audio	None
Dolby Digital	Dolby ATMOS
Digital Out (S/PDIF)	No
Speaker Power Rating	2W@4ohm/ch
Type	180W Type-C PD 3.1 EPR AC Adapter
Dimensions	(139.5 x 69 x 22mm)
Weight	Max 430g
Input Voltage	100-240V
TPM	Version 2.0
Asset ID	Yes
vPro	Intel vPro for WS
Format	16" Clamshell
Color & Material	Black Aluminum
Thermal Solutions	Internal Dual Fan, Flex Cooling, Intelligent Cooling, Dual by-pass design
Dimensions	Length 14.25 inches 362 millimeters Width 9.92 inches 252 millimeters Height 0.62 (front) / 0.82 (rear), 1.17 (max) inches 15.8 (front) / 20.9 (rear), 29.8 (max) millimeters
Weight	5.6lbs/2.54kg
Height (mm)	330
Height (inch)	12.992
Width (mm)	510
Width (inch)	20.079
Depth (mm)	96
Depth (inch)	3.78
Weight (kgs)	start from 4.03 kg
Weight (lbs)	start from 8.866 lbs
Hardware Maintenance Manual	P16 Gen 3 HMM
Drivers & Software	P16 Gen 3 Drivers & Software
Self Healing BIOS	Yes
Access Panel	Removeable bottom cover

Number of Screws	23 Total 1.D cover with screw->9PCS 2.Battery with screw->4PCS 3.SSD Gen5 BKT with screw->1PCS + C SSD BKT assy with screw-> 4PCS 4.SSD Gen4 CRU mylar with screw->2PCS 5.WWAN BKT with screw->1PCS+ C WWAN BKT assy with screw->2PCS
Swappable Components	Bottom cover, battery, M.2 Solid State Drive, SoDIMM memory module, WWAN module, SIM tray, keyboard, RTC battery
Storage Slots	3 slots
Memory	4 slots
System Board	FR4 & HDI (GPU B1)
Restore CD/DVD/USB Set	None, Restore Media available via Lenovo Customer Support Center
Cable Lock Support	Security-lock slot, Optional Kensington Cable Lock
Power-On Password	Yes
Hard Disk Password	Yes; User and Master hard disk password
Supervisor Password	Yes
NIC LEDs (integrated)	Yes
Security Chip	Yes (for TMP 2.0)
Access Panel Key Lock	Bottom Cover Tamper Detection
Boot Sequence Control	Yes
Operating – Air Temperature	Meet MIL810G At altitude 15,000 feet for 1 hour 43°C for 2hrs -21°C for 2hrs
Non Operating – Air Temperature	Meet MIL810G At altitude 15,000 feet for 1 hour 63°C for 4hrs -25°C for 24hrs
Humidity	Meet MIL810G 95% RH, 30~60C, 24hrs*10cycles
Corrosive Gas	G1
Particulates	P1
Processor	Intel® Core™ Ultra 5 245HX processor (E-cores up to 4.5 GHz P-cores up to 5.1 GHz) Intel® Core™ Ultra 7 255HX processor (E-cores up to 4.5 GHz P-cores up to 5.2 GHz) Intel® Core™ Ultra 7 265HX processor (E-cores up to 4.6 GHz P-cores up to 5.3 GHz) Intel® Core™ Ultra 9 275HX processor (E-cores up to 4.6 GHz P-cores up to 5.4 GHz) Intel® Core™ Ultra 9 285HX processor (E-cores up to 4.6 GHz P-cores up to 5.5 GHz)
Memory Support	DDR5 SoDIMM ECC/non-ECC Native: 5600MT/s Actual: 4800MT/s
Chipset (PCH)	Mobile Intel® HM880 Chipset
Size of BIOS Flash	64MB

Super I/O	None
Clock	Crystal
Audio	Dolby Atmos
Ethernet	Full size 2.5Gbps RJ-45 port
System Capacity Options	16GB (16GB*1 or 8GB*2) 32GB (32GB*1 or 16GB*2 or 8GB*4) 48GB (42GB*1) 64GB (32GB*2 or 16GB*4) 96GB (48GB*2) 128GB (32GB*4) 192GB (48GB*4)
Memory Types	8GB DDR5 5600MT/s SoDIMM non-ECC 16GB DDR5 5600MT/s SoDIMM non-ECC 32GB DDR5 5600MT/s SoDIMM non-ECC 48GB DDR5 5600MT/s SoDIMM non-ECC 16GB DDR5 5600MT/s SoDIMM ECC 32GB DDR5 5600MT/s SoDIMM ECC
Brand of Memory	Samsung Micron SK Hynix Ramaxel
Memory clock frequency(MHz)	Native: 5600MT/s, Operational: 4800MT/s
2.5" SAS Hard Disk Drive (HDD)	None
2.5" SATA Hard Disk Drive (HDD)	None
2.5" SATA Solid State Drive (SSD)	None
M.2 (NGFF) PCIe Solid State Drive (SSD)	256GB OPAL2 PCIe 4×4 Value TLC (M.2 2280-S3) 512GB OPAL2 PCIe 4×4 Value TLC (M.2 2280-S3) 1TB OPAL2 PCIe 4×4 Value TLC (M.2 2280-S3) 512GB OPAL2 PCIe 5×4 Performance TLC (M.2 2280-S3) 1TB OPAL2 PCIe 5×4 Performance TLC (M.2 2280-S3) 2TB OPAL2 PCIe 5×4 Performance TLC (M.2 2280-S3) 4TB OPAL2 PCIe 5×4 Performance TLC (M.2 2280-S3)
2.5" PCIe Solid State Drive (SSD)	None
Brand of Drive	Samsung Union Memory SanDisk Micron Hynix
Intel Optane Storage Technology	None
RAID	Optional, Selectable in BIOS
RAID Level and Requirements	RAID-0/1/5
Media Card Reader Specifications	SD Express 8.0
Disclaimers	Backwards compatible with UHS-I and UHS-II

CPU	Intel® Core™ Ultra 5 245HX processor (E-cores up to 4.5 GHz P-cores up to 5.1 GHz)	Intel® Core™ Ultra 7 255HX processor (E-cores up to 4.5 GHz P-cores up to 5.2 GHz)	Intel® Core™ Ultra 7 265HX processor (E-cores up to 4.6 GHz P-cores up to 5.3 GHz)	Intel® Core™ Ultra 9 275HX processor (E-cores up to 4.6 GHz P-cores up to 5.4 GHz)	Intel® Core™ Ultra 9 285HX processor (E-cores up to 4.6 GHz P-cores up to 5.5 GHz)

Integrated Graphics	Intel® Arc Pro Graphics	Intel® Arc Pro Graphics	Intel® Arc Pro Graphics	Intel® Arc Pro Graphics	Intel® Arc Pro Graphics
# of Cores	4 P-cores and 8 E-cores	8 P-cores and 12 E-cores	8 P-cores and 12 E-cores	8 P-cores and 16 E-cores	8 P-cores and 16 E-cores
# of Threads	14	20	20	24	24
Processor Base Frequency	E-cores up to 2.6 GHz / P-cores up to 3.1 GHz	E-cores up to 1.8 GHz / P-cores up to 2.4 GHz	E-cores up to 2.3 GHz / P-cores up to 2.6 GHz	E-cores up to 2.1 GHz / P-cores up to 2.7 GHz	E-cores up to 2.1 GHz / P-cores up to 2.8 GHz
Max Turbo Frequency	E-cores up to 4.5 GHz / P-cores up to 5.1 GHz	E-cores up to 4.5 GHz / P-cores up to 5.2 GHz	E-cores up to 4.6 GHz / P-cores up to 5.3 GHz	E-cores up to 4.6 GHz / P-cores up to 5.4 GHz	E-cores up to 4.6 GHz / P-cores up to 5.5 GHz
Cache	24 MB	30 MB	30 MB	36 MB	36 MB
TDP	45 W	45 W	45 W	45 W	45 W

Display Specifications

Model	WUXGA IPS Non-Touch, Low Power	WQUXGA IPS Non-Touch	3.2k Tandem-OLED Touch
Resolution	FHD+ (1920 x 1200)	UHD+ (3840 x 2400)	3.2k (3200 x 2000)
Diagonal	16"	16"	16"
Aspect Ratio	16:10	16:10	16:10
Backlight	LED	LED	N/A
PPI	142	283	236
Active Area	FHD+: 344.68mm x 215.42mm	UHD+: 344.678mm x 215.424mm	3.2k: 344.448mm x 215.280mm
Refresh Rate	Max 60Hz	Max 60Hz	40-120Hz VRR
Contrast Ratio	FHD+: 1200:1	UHD+: 1500:1	3.2k: 100,000:1
Viewing Angle (*1)	FHD+: 89/89/89/89 degree	UHD+: 85/85/85/85 degree	3.2k: 85/85/85/85 degree
Color gamut	100% sRGB	100% DCI-P3	100% DCI-P3
Brightness	500 nits	800 nits	SDR 600 nits / HDR 1500 nits
HDR	N/A	HDR400 Dolby Vision	HDR600 Dolby Vision
Color Depth	FHD+: 16.7M (8-bit)	UHD+: 1064M (8-bit + 2 FRC)	3.2k: 1074M (8-bit + 2 FRC)
Interface	FHD+: eDP 1.4b	UHD+: eDP 1.4b	3.2k: eDP 1.4b
Panel ID Recognition	EDID in BIOS Table	EDID in BIOS Table	EDID in BIOS Table
Weight	320g max	330g max	199g max
Color Calibrator	X-Rite Factory Color Calibration	X-Rite Factory Color Calibration	X-Rite Factory Color Calibration
Panel Technology	IPS, Anti-Glare	IPS, Anti-Glare	Tandem-OLED, AGARAS

Touch Panel	None	None	Multi-Finger Touch Panel

SSD Specifications

2.5" SATA Solid State Drive (SSD)	N/A
M.2 (NGFF) PCIe Solid State Drive (SSD)	3x M.2 2280-S3 PCIe
2.5" PCIe Solid State Drive (SSD)	N/A
Intel Optane Storage Technology	N/A

Solid State Storage Devices

Supported Types	M.2	M.2
Dimensions inches/centimeters (W x D x H)	22.0 (+-0.15) x 80.0 (+-0.15) x 2.3 (max)	22.0 (+-0.15) x 80.0 (+-0.15) x 2.3 (max)
Size	M.2 2280-S3	M.2 2280-S3
Interface Type	PCIe NVMe	PCIe NVMe
Read/Write IOPS Specifications	Read: 600K (1TB), 450K (512GB), 250K (256GB) Write: 500K (1TB,512GB), 400K (256GB) IOPS, 4K Random, 8 threads, queue depth of 32, data set size of 1GB.	Read: 1500K (4TB/2TB), 1200K (1TB), 1000K (512GB) Write: 1500K (4TB/2TB/1TB), 1200K (512GB) IOPS, 4K Random, 8 threads, queue depth of 32, data set size of 1GB.
Bandwidth Performance	PCIe Gen4x4 Value – 256GB-1TB	PCIe Gen5x4 Performance – 512GB-4TB
Power Consumption (Max)	3.0A (duration for 10 us)	4.5A (duration for 10 us)
Active(AVG)	5W	10W
Idle	5mW (L1.2)	5mW (L1.2)
Min MTBF	2,000,000 (h)	2,000,000 (h)
Min Sequential Read	5000MB/s (1TB), 4800MB/s (512GB), 4000MB/s (256GB)	14000MB/s (4TB/2TB/1TB), 11000MB/s (512GB)
Min Sequential Write	4000MB/s (1TB/512GB), 2000MB/s (256GB)	12000MB/s (4TB/2TB), 11000MB/s (1TB), 5500MB/s (512GB)
Hardware Encryption	OPAL	OPAL

Discrete Graphics Adapter

Laptop GPUs	NVIDIA RTX PRO 1000 Blackwell Laptop GPU	NVIDIA RTX PRO 2000 Blackwell Laptop GPU	NVIDIA RTX PRO 3000 Blackwell Laptop GPU	NVIDIA RTX PRO 4000 Blackwell Laptop GPU	NVIDIA RTX PRO 5000 Blackwell Laptop GPU
NVIDIA CUDA Processing Cores	2560	3328	5888	7680	10496

NVIDIA RT Cores	4th Gen	4th Gen	4th Gen	4th Gen	4th Gen
Tensor Cores	5th Gen	5th Gen	5th Gen	5th Gen	5th Gen
GPU Memory	8GB	8GB	12GB	16GB	24GB
Peak Memory Bandwidth	384 GB/s	384 GB/s	672 GB/s	896 GB/s	896 GB/s
Memory Type	GDDR7	GDDR7	GDDR7	GDDR7	GDDR7
Memory Interface	128-bit	128-bit	192-bit	256-bit	256-bit
DisplayPort	2.1b	2.1b	2.1b	2.1b	2.1b
Open GL	4.6	4.6	4.6	4.6	4.6
Shader Model	7	7	7	7	7
DirectX	12 Ultimate	12 Ultimate	12 Ultimate	12 Ultimate	12 Ultimate
PCIe Generation	5	5	5	5	5
Single Precision Floating-Point Performance	13.6	17.7	29.1	38.7	49.8
Tensor Performance	193	231.6	231.6	231.6	231.6
NVIDIA FXAA/TXAA Anti-Aliasing	Yes	Yes	Yes	Yes	Yes
NVIDIA RTX Desktop Manager	No	No	No	No	No
Vulkan Support	Yes	Yes	Yes	Yes	Yes
NVIDIA Optimus	Yes	Yes	Yes	Yes	Yes
NVIDIA Max-Q Technology	Yes	Yes	Yes	Yes	Yes
NVENC/NVDEC	Yes	Yes	Yes	Yes	Yes

WLAN

Model	Intel Wi-Fi 7 BE200 (Gale Peak 2) + BT5.4 (HW Ready)
Connector: Main, Aux/GNSS, GNSS	ANT1:Wi-Fi+Bluetooth ; ANT2:Wi-Fi
Antenna Diversity	Supported
MIMO	Supported
GNSS Bian	N/A
Radio ON/OFF Control	Supported
Connector interface	M.2 PCIe + USB

Operating Temperature (Adapter Shield)	0c to +50c
Humidity Non-Operating	50%~90% Rh non condensing (at temperatures of 25c to 35c)
Operating Systems	Microsoft Windows 11, Linux
Wi-Fi Alliance	n/a
IEEE WLAN Standard	IEEE 802.11a/b/g/n/ac/ax/be
Roaming	Support seamless roaming between access points
Bluetooth*	Bluetooth 5.4
Authentication Protocols	802.1X EAP-TLS, EAP-TTLS/MSCHAPv2, PEAPv0 - MSCHAPv2 (EAP-SIM, EAP-AKA, EAP-AKA')
Encryption	128-bit AES-CCMP, 256-bit AES-GCMP
Regulatory	For a list of country approvals, please contact your local Intel representatives.
US Government	FIPS 140-2
Product Safety	UL,C-UL,CB (IEC62368-1)
Disclaimers	1) 6GHz channel of Wi-Fi 6E is only available with Windows 11 2) Bluetooth may be limited by OS

Battery

Dimension	L: 310mm*W: 44.5mm*T 12.7mm
Weight	Max 365g
Type (Chemistry and Cell)	Li-Polymer (4S1P), 4-cell
Voltage	15.6 V
Battery Capacity	99.9Wh
Charging Time	On Charge Time (0- 100%) * 113min Off Charge Time (0 – 80%) ** 57 min Off Charge Time (0 – 100%) ** 109 min
Operating Temperature Range	between 10°C (50°F) and 35°C (95°F)
Warranty	1 Year / 3 Year Available
Coin Cell Battery (Model)	CR2032

SECTION IV: BIOS / Certifications / Standards / Environmental

BIOS Specifications

WMI Support	Yes, if it is BIOS Setup change by WMI.

ROM-Based Setup Utility (F1)	Yes
Bootblock Recovery	Support NIST
Replicated Setup	Yes, it supported with SRSETUP tool.
Boot Control	Yes, it means Boot order change.
Discrete Mode	Support Discrete Mode
Memory Change Alert	N/A
Thermal Alert	N/A
Asset Tag	Yes
System/Emergency ROM Flash Recovery with Video	N/A
Remote Wakeup/Remote Shutdown	Only support WOL when system is connected with Dock.
Keyboard-less Operation	N/A
Per-port Control	Yes, if it is I/O port enable/disable by BIOS Setup.
Adaptive Cooling	Yes, if it is thermal & fan control.
Security	Yes, BIOS password / Hard disk password / Finger print
Intel(R) AMT (includes ASF 2.0)	Yes. If you select vPro model
Intel(R) TXT	Yes. If you select vPro model
Memory Modes	N/A
UEFI	UEFI 2.9A

EMC & Safety

EMC	Published, Certified Existing Reports EMC – Australia EMC – Canada EMC – China EMC – EU/EFTA EMC – Japan EMC – Kazakhstan EMC – New Zealand EMC – South Korea EMC – Taiwan EMC – USA/Territories Not Applicable / Not Required EMC – Israel EMC – Moldova EMC – Serbia EMC – Turkey EMC – Uzbekistan EMC – Vietnam
Safety	To access the latest User Guide and Safety and Warranty Guide, go to: https://support.lenovo.com Low Halogen Declaration of Conformance TNOT-2017-0040 Section 9 – Low Halogen Scorecard Homologation PCRB Compliant In the following countries: Albania, Algeria, Andorra, Angola, Antigua and Barbuda, Argentina, Armenia, Aruba, Australia, Azerbaijan, Bahamas,

	Bahrain, Bangladesh, Barbados, Belarus, Belize, Benin, Bermuda, Bolivia, Botswana, Burkina Faso, Burundi, Cambodia, Cameroon, Canada, Cape Verde, Cayman Islands, Central African Republic, Chad, China, Colombia, Comoros, Congo, Costa Rica, Dijbouti, Dominican Republic, Egypt, El Salvador, Eritrea, Ethiopia, EU/EFTA, Fiji, Gabon, Gambia, Georgia, Ghana, Grenada, Guatemala, Guinea, Haiti, Honduras, Hong Kong, India, Indonesia, Israel, Jamaica, Japan, Jordan, Kazakhstan, Kenya, Kuwait, Laos, Lebanon, Liberia, Macau, Madagascar, Malawi, Malaysia, Mali, Mauritania, Mauritius, Mexico, Moldova, Mongolia, Morocco, Mozambique, Namibia, Nepal, New Zealand, Nicaragua, Niger, Nigeria, Oman, Pakistan, Panama, Papua New Guinea, Paraguay, Peru, Philippines, Qatar, Russia, Saudi Arabia, Senegal, Serbia, Seychelles, Sierra Leone, Singapore, South Africa, South Korea, Sri Lanka, Swaziland, Taiwan, Tajikistan, Tanzania, Thailand, Togo, Tunisia, Turkey, Turkmenistan, Uganda, Ukraine, United Arab Emirates, Uruguay, USA/Territories, Uzbekistan, Venezuela, Vietnam, Zambia, Zimbabwe, Brazil – Inmetro 170 Govt Bids, Guinea-Bissau, Lesotho

Environmentals

Energy Star	ENERGY STAR® Version 9.0 For more information about ENERGY STAR, go to: https://www.energystar.gov
EPEAT	EPEAT Gold Certification Available on select models
IT ECO declaration	The latest environmental information about Lenovo products is available at: https://www.lenovo.com/us/en/compliance/eco-declaration/
Hazardous Substances	The latest environmental information about Lenovo products is available at: https://www.lenovo.com/ecodeclaration European Union RoHS This Lenovo product, with included parts (cables, cords, and so on) meets the requirements of Directive 2011/65/EU on the restriction of the use of certain hazardous substances in electrical and electronic equipment (“RoHS recast” or “RoHS 2”). For more information about Lenovo worldwide compliance on RoHS, go to: https://www.lenovo.com/content/dam/lenovo/site-design/esg-document-library/global/corp-policies/materials/Lenovo_Commitment_to_RoHS.pdf

Manageability

Industry Standard Specifications	This product meets the following industry standard specifications for manageability functionality:
Remote Manageability Software Solutions	Lenovo ThinkManagement Console Microsoft System Center Configuration Manager

	LANDesk Management Suite for Lenovo Vantage Technologies (www.landesk.com/lenovo)
System Software Manager	Lenovo ThinkStation supports software management tools from the ThinkVantage System Update suite: System Update Update Retriever
Service, Support, and Warranty	On-site Warranty and Service: Three-years, limited warranty and service offering delivers on-site service for parts and labor and includes free telephone support 8am â€“ 5pm. Global coverage ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering.
Materials Used	50% Recycled Aluminum A Cover 90% Recycled Magnesium Aluminum C Cover 55% Recycled Aluminum D Cover 85% PCC Plastic Key Caps (non-Black Keyboard) 90% PCC Plastic Speaker Enclosure 97% PCC Plastic Battery Pack Enclosure 90% PCC Plastic 180W Slim AC Adapter Low Temperature Solder (SSD, fingerprint reader module, FHD+ panel) Plastic free packaging with 90% recycled and/or FSC certified content (standard/bulk)
TCO Certification	TCO 10.0
Disclaimers	1. EPEAT registered where applicable. EPEAT registration varies by country. See www.epeat.net for registration status by country. 2. Product packaging shall contain, on average, a minimum total percentage of 90% by weight of any combination of the following materials: Recycled content, biobased plastic, non-wood biobased fiber material, and/or sustainably forested material